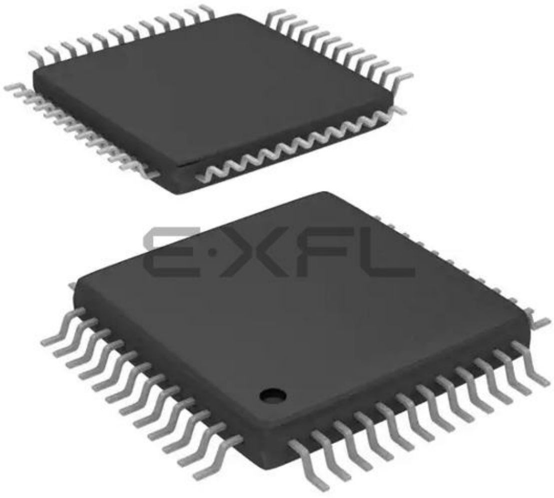
Silicon Labs - EFM32G222F64-QFP48T Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	37
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 4x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32g222f64-qfp48t

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output low voltage (Production test condition = 3.0 V, DRIVEMODE = STANDARD)	V_{IOOL}	Sinking 0.1 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	0.20×V_{DD}	—	V
		Sinking 0.1 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	0.10×V_{DD}	—	V
		Sinking 1 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOW	—	0.10×V_{DD}	—	V
		Sinking 1 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOW	—	0.05×V_{DD}	—	V
		Sinking 6 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	—	—	0.30×V_{DD}	V
		Sinking 6 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	—	—	0.20×V_{DD}	V
		Sinking 20 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = HIGH	—	—	0.35×V_{DD}	V
		Sinking 20 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = HIGH	—	—	0.25×V_{DD}	V
Input leakage current	I_{IOLEAK}	High Impedance IO connected to GROUND or V_{DD}	—	±0.1	±40	nA
I/O pin pull-up resistor	R_{PU}		—	40	—	kΩ
I/O pin pull-down resistor	R_{PD}		—	40	—	kΩ
Internal ESD series resistor	R_{IOESD}		—	200	—	Ω
Pulse width of pulses to be removed by the glitch suppression filter	$t_{IOGLITCH}$		10	—	50	ns
Output fall time	t_{IOOF}	GPIO_Px_CTRL DRIVEMODE = LOWEST and load capacitance C_L=12.5-25pF.	20+0.1C_L	—	250	ns
		GPIO_Px_CTRL DRIVEMODE = LOW and load capacitance C_L=350-600pF	20+0.1C_L	—	250	ns
I/O pin hysteresis (V_{IOTHR+} - V_{IOTHR-})	V_{IOHYST}	V_{DD} = 1.98 - 3.8 V	0.1×V_{DD}	—	—	V

Note:

1. If the GPIO input voltage is between 0.3×V_{DD} and 0.7×V_{DD}, the current consumption will increase.

4.9 Oscillators

4.9.1 LFXO

Table 4.8. LFXO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supported nominal crystal frequency	f_{LFXO}		—	32.768	—	kHz
Supported crystal equivalent series resistance (ESR)	ESR_{LFXO}		—	30	120	kOhm
Supported crystal external load range	C_{LFXOL}		X[1]	—	25	pF
Current consumption for core and buffer after startup	I_{LFXO}	ESR=30 kΩ, C_L=10 pF, LFXOBOOST in CMU_CTRL is 1	—	190	—	nA
Start-up time	t_{LFXO}	ESR=30 kΩ, C_L=10 pF, 40% - 60% duty cycle has been reached, LFXOBOOST in CMU_CTRL is 1	—	400	—	ms

Note:

1. See Minimum Load Capacitance (C_{LFXOL}) Requirement For Safe Crystal Startup in Configurator in Simplicity Studio.

For safe startup of a given crystal, the Configurator tool in Simplicity Studio contains a tool to help users configure both load capacitance and software settings for using the LFXO. For details regarding the crystal configuration, the reader is referred to application note "AN0016 EFM32 Oscillator Design Consideration".

4.9.4 HFRCO

Table 4.11. HFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency, V_{DD}= 3.0 V, T_{AMB}=25 °C	f_{HFRCO}	28 MHz frequency band	27.16	28	28.84	MHz
		21 MHz frequency band	20.37	21	21.63	MHz
		14 MHz frequency band	13.58	14	14.42	MHz
		11 MHz frequency band	10.67	11	11.33	MHz
		7 MHz frequency band	6.402	6.6[1]	6.798	MHz
		1 MHz frequency band	1.164	1.2[2]	1.236	MHz
Settling time	$t_{HFRCO\_settling}$	After start-up, f_{HFRCO} = 14 MHz	—	0.6	—	Cycles
		After band switch	—	25	—	Cycles
Current consumption (Production test condition = 14 MHz)	I_{HFRCO}	f_{HFRCO} = 28 MHz	—	158	190	µA
		f_{HFRCO} = 21 MHz	—	125	155	µA
		f_{HFRCO} = 14 MHz	—	99	120	µA
		f_{HFRCO} = 11 MHz	—	88	110	µA
		f_{HFRCO} = 6.6 MHz	—	72	90	µA
		f_{HFRCO} = 1.2 MHz	—	24	32	µA
Duty cycle	DC_{HFRCO}	f_{HFRCO} = 14 MHz	48.5	50	51	%
Frequency step for LSB change in TUNING value	$TUNESTEP_{HFRCO}$		—	0.3[3]	—	%

Note:

1. For devices with prod. rev. < 19, Typ = 7 MHz and Min/Max values not applicable.
2. For devices with prod. rev. < 19, Typ = 1 MHz and Min/Max values not applicable.
3. The TUNING field in the CMU_HFRCOCTRL register may be used to adjust the HFRCO frequency. There is enough adjustment range to ensure that the frequency bands above 7 MHz will always have some overlap across supply voltage and temperature. By using a stable frequency reference such as the LFXO or HFXO, a firmware calibration routine can vary the TUNING bits and the frequency band to maintain the HFRCO frequency at any arbitrary value between 7 MHz and 28 MHz across operating conditions.

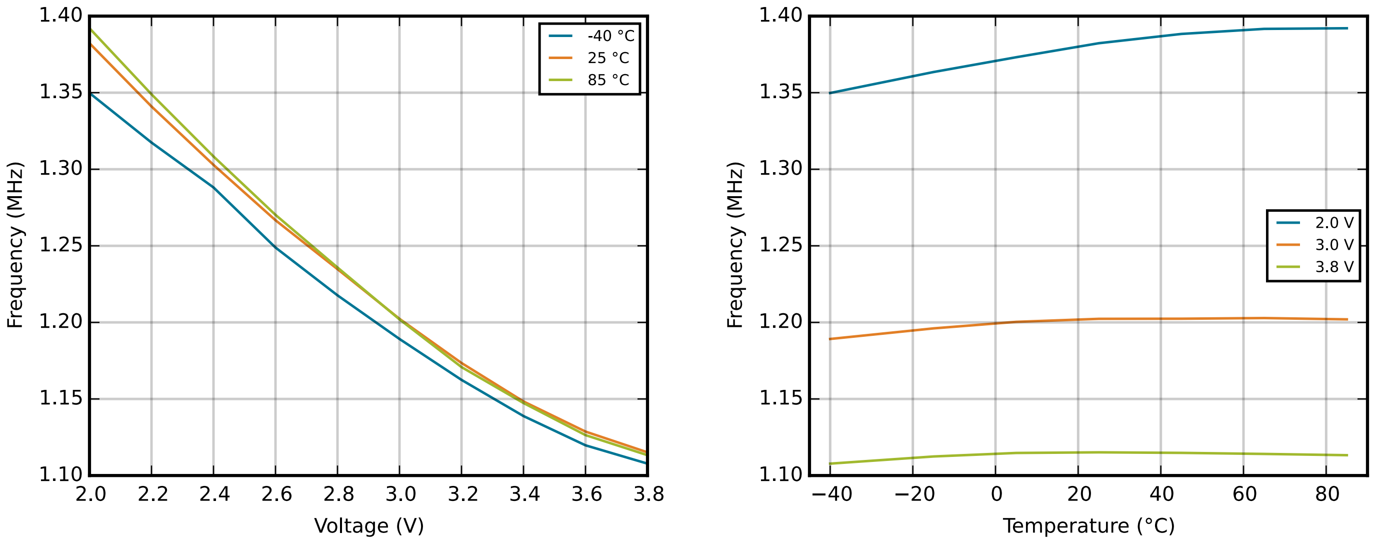

Figure 4.21. Calibrated HFRCO 1 MHz Band Frequency vs Supply Voltage and Temperature

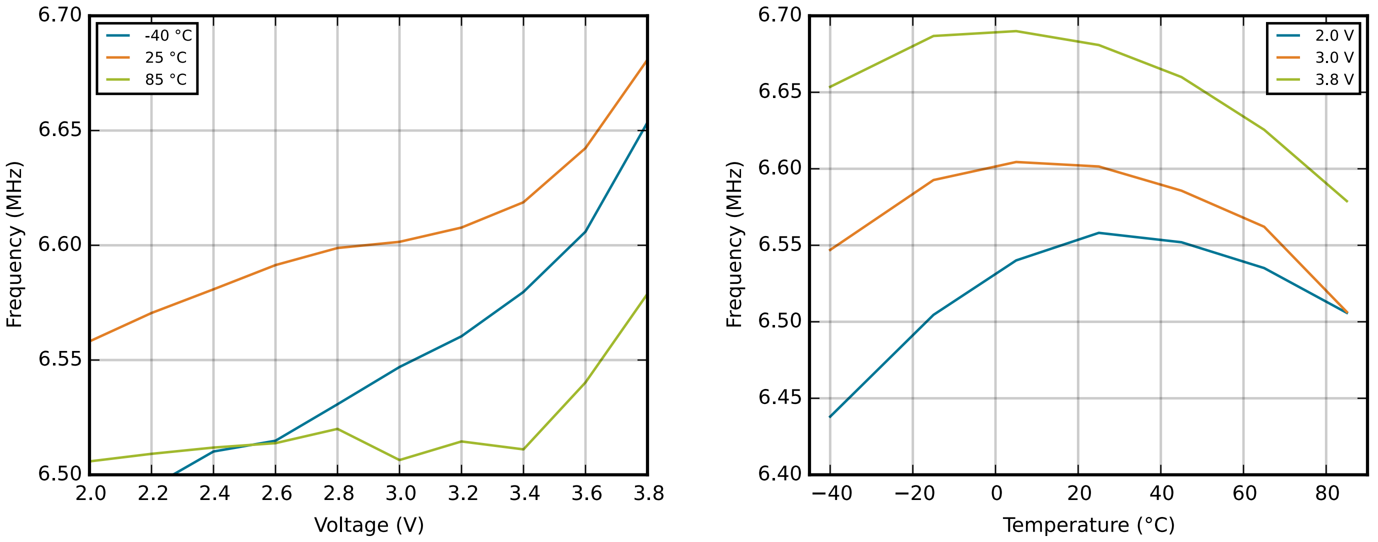

Figure 4.22. Calibrated HFRCO 7 MHz Band Frequency vs Supply Voltage and Temperature

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range (SFDR)	SFDR_{ADC}	200 kSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	68	79	—	dBc
		200 kSamples/s, 12 bit, differential, 2xV_{DD} reference,ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
Offset voltage	$V_{\text{ADCOFFSET}}$	After calibration, single-ended	—	0.3	—	mV
		After calibration, differential	-4	0.3	4	mV
Thermometer output gradient	$\text{TGRAD}_{\text{ADCTH}}$		—	-1.92	—	mV/°C
			—	-6.3	—	ADC Codes/°C
Differential non-linearity (DNL)	DNL_{ADC}	V_{DD}= 3.0 V, external 2.5 V reference	-1	±0.7	4	LSB
Integral non-linearity (INL), End point method	INL_{ADC}	V_{DD}= 3.0 V, external 2.5 V reference	—	±1.2	±3	LSB
Missing codes	MC_{ADC}		—	—	3	LSB
Gain error drift	GAIN_{ED}	1.25 V reference	—	0.01[2]	0.033[3]	%/°C
		2.5 V reference	—	0.01[2]	0.03[3]	%/°C
Offset error drift	$\text{OFFSET}_{\text{ED}}$	1.25 V reference	—	0.00[2]	0.06[3]	LSB/°C
		2.5 V reference	—	0.00[2]	0.04[3]	LSB/°C
VREF voltage	V_{REF}	1.25 V reference	1.2	1.25	1.3	V
		2.5 V reference	2.4	2.5	2.6	V
VREF voltage drift	$V_{\text{REF\_VDRIFT}}$	1.25 V reference	-12.4	2.9	18.2	mV/V
		2.5 V reference, VDD > 2.5 V	-24.6	5.7	35.2	mV/V
VREF temperature drift	$V_{\text{REF\_TDRIFT}}$	1.25 V reference	-132	272	677	µV/°C
		2.5 V reference	-231	545	1271	µV/°C
VREF current consumption	I_{VREF}	1.25 V reference	—	67	114	µA
		2.5 V reference	—	55	82	µA
ADC and DAC VREF matching	$V_{\text{REF\_MATCH}}$	1.25 V reference	—	99.85	—	%
		2.5 V reference	—	100.01	—	%

Note:

1. Includes required contribution from the voltage reference.
2. Typical numbers given by abs(Mean) / (85 - 25).
3. Max number given by (abs(Mean) + 3x stddev) / (85 - 25).

The integral non-linearity (INL) and differential non-linearity parameters are explained in the following figures.

4.14 LCD

Table 4.18. LCD

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frame rate	f_{LCDFR}		30	—	200	Hz
Number of segments supported	NUM_{SEG}		—	4×40	—	seg
LCD supply voltage range	V_{LCD}	Internal boost circuit enabled	2.0	—	3.8	V
Steady state current consumption.	I_{LCD}	Display disconnected, static mode, framerate 32 Hz, all segments on.	—	250	—	nA
		Display disconnected, quadruplex mode, framerate 32 Hz, all segments on, bias mode to ONE-THIRD in LCD_DISPCTRL register.	—	550	—	nA
Steady state Current contribution of internal boost.	$I_{LCDBOOST}$	Internal voltage boost off	—	0	—	µA
		Internal voltage boost on, boosting from 2.2 V to 3.0 V.	—	8.4	—	µA
Boost Voltage	V_{BOOST}	VBLEV of LCD_DISPCTRL register to LEVEL0	—	3.0	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL1	—	3.08	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL2	—	3.17	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL3	—	3.26	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL4	—	3.34	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL5	—	3.43	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL6	—	3.52	—	V
		VBLEV of LCD_DISPCTRL register to LEVEL7	—	3.6	—	V

The total LCD current is given by the following equation. $I_{LCDBOOST}$ is zero if internal boost is off.

$$I_{LCDTOTAL} = I_{LCD} + I_{LCDBOOST}$$

4.15 I2C

Table 4.19. I2C Standard-mode (Sm)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	100[1]	kHz
SCL clock low time	t_{LOW}	4.7	—	—	µs
SCL clock high time	t_{HIGH}	4.0	—	—	µs
SDA set-up time	$t_{SU,DAT}$	250	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	3450[2,3]	ns
Repeated START condition set-up time	$t_{SU,STA}$	4.7	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	4.0	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	4.0	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	4.7	—	—	µs

Note:

1. For the minimum HFPERCLK frequency required in Standard-mode, see the I2C chapter in the EFM32G Reference Manual.
2. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).
3. When transmitting data, this number is guaranteed only when I2Cn_CLKDIV < ((3450*10^{-9} [s] * $f_{HFPERCLK}$ [Hz]) - 4).

Table 4.20. I2C Fast-mode (Fm)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	400[1]	kHz
SCL clock low time	t_{LOW}	1.3	—	—	µs
SCL clock high time	t_{HIGH}	0.6	—	—	µs
SDA set-up time	$t_{SU,DAT}$	100	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	900[2,3]	ns
Repeated START condition set-up time	$t_{SU,STA}$	0.6	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	0.6	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	0.6	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	1.3	—	—	µs

Note:

1. For the minimum HFPERCLK frequency required in Fast-mode, see the I2C chapter in the EFM32G Reference Manual.
2. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).
3. When transmitting data, this number is guaranteed only when I2Cn_CLKDIV < ((900*10^{-9} [s] * $f_{HFPERCLK}$ [Hz]) - 4).

Table 5.1. Device Pinout

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
0	VSS	Ground.			
1	PA0		TIM0_CC0 #0/1	I2C0_SDA #0	
2	PA1		TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_1	Digital IO power supply 1.			
5	PC0	ACMP0_CH0	PCNT0_S0IN #2	US1_TX #0	
6	PC1	ACMP0_CH1	PCNT0_S1IN #2	US1_RX #0	
7	PB7	LFXTAL_P		US1_CLK #0	
8	PB8	LFXTAL_N		US1_CS #0	
9	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
10	PB11	DAC0_OUT0	LETIM0_OUT0 #1		
11	AVDD_2	Analog power supply 2.			
12	PB13	HFXTAL_P		LEU0_TX #1	
13	PB14	HFXTAL_N		LEU0_RX #1	
14	IOVDD_3	Digital IO power supply 3.			
15	AVDD_0	Analog power supply 0.			
16	PD4	ADC0_CH4		LEU0_TX #0	
17	PD5	ADC0_CH5		LEU0_RX #0	
18	PD6	ADC0_CH6	LETIM0_OUT0 #0	I2C0_SDA #1	
19	PD7	ADC0_CH7	LETIM0_OUT1 #0	I2C0_SCL #1	
20	VDD_DREG	Power supply for on-chip voltage regulator.			
21	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
22	PC13	ACMP1_CH5	TIM0_CDTI0 #1/3 TIM1_CC0 #0 PCNT0_S0IN #0		
23	PC14	ACMP1_CH6	TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0		
24	PC15	ACMP1_CH7	TIM0_CDTI2 #1/3 TIM1_CC2 #0		DBG_SWO #1
25	PF0		LETIM0_OUT0 #2		DBG_SWCLK #0/1
26	PF1		LETIM0_OUT1 #2		DBG_SWDIO #0/1
27	PF2				ACMP1_O #0 DBG_SWO #0
28	IOVDD_5	Digital IO power supply 5.			
29	PE10		TIM1_CC0 #1	US0_TX #0	BOOT_TX
30	PE11		TIM1_CC1 #1	US0_RX #0	BOOT_RX

QFN64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
40	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
41	PC8	ACMP1_CH0	TIM2_CC0 #2	US0_CS #2	
42	PC9	ACMP1_CH1	TIM2_CC1 #2	US0_CLK #2	
43	PC10	ACMP1_CH2	TIM2_CC2 #2	US0_RX #2	
44	PC11	ACMP1_CH3		US0_TX #2	
45	PC12	ACMP1_CH4			CMU_CLK0 #1
46	PC13	ACMP1_CH5	TIM0_CDTI0 #1/3 TIM1_CC0 #0 PCNT0_S0IN #0		
47	PC14	ACMP1_CH6	TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0		
48	PC15	ACMP1_CH7	TIM0_CDTI2 #1/3 TIM1_CC2 #0		DBG_SWO #1
49	PF0		LETIM0_OUT0 #2		DBG_SWCLK #0/1
50	PF1		LETIM0_OUT1 #2		DBG_SWDIO #0/1
51	PF2				ACMP1_O #0 DBG_SWO #0
52	PF3		TIM0_CDTI0 #2		
53	PF4		TIM0_CDTI1 #2		
54	PF5		TIM0_CDTI2 #2		
55	IOVDD_5	Digital IO power supply 5.			
56	PE8		PCNT2_S0IN #1		
57	PE9		PCNT2_S1IN #1		
58	PE10		TIM1_CC0 #1	US0_TX #0	BOOT_TX
59	PE11		TIM1_CC1 #1	US0_RX #0	BOOT_RX
60	PE12		TIM1_CC2 #1	US0_CLK #0	
61	PE13			US0_CS #0	ACMP0_O #0
62	PE14			LEU0_TX #2	
63	PE15			LEU0_RX #2	
64	PA15				

TQFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
6	PA5		TIM0_CDTI2 #0	LEU1_TX #1	
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PC0	ACMP0_CH0	PCNT0_S0IN #1	US1_TX #1	
10	PC1	ACMP0_CH1	PCNT0_S1IN #1	US1_RX #1	
11	PC2	ACMP0_CH2		US1_CLK #1	
12	PC3	ACMP0_CH3		US1_CS #1	
13	PC4	ACMP0_CH4	LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
14	PC5	ACMP0_CH5	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
15	PB7	LFXTAL_P		US1_CLK #0	
16	PB8	LFXTAL_N		US1_CS #0	
17	PA8		TIM2_CC0 #0		
18	PA9		TIM2_CC1 #0		
19	PA10		TIM2_CC2 #0		
20	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0	LETIM0_OUT0 #1		
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		LEU0_TX #1	
25	PB14	HFXTAL_N		LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			
27	AVDD_0	Analog power supply 0.			
28	PD0	ADC0_CH0	PCNT2_S0IN #0	US1_TX #1	
29	PD1	ADC0_CH1	TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
30	PD2	ADC0_CH2	TIM0_CC1 #3	US1_CLK #1	
31	PD3	ADC0_CH3	TIM0_CC2 #3	US1_CS #1	
32	PD4	ADC0_CH4		LEU0_TX #0	
33	PD5	ADC0_CH5		LEU0_RX #0	
34	PD6	ADC0_CH6	LETIM0_OUT0 #0	I2C0_SDA #1	
35	PD7	ADC0_CH7	LETIM0_OUT1 #0	I2C0_SCL #1	
36	PD8				CMU_CLK1 #1
37	PC6	ACMP0_CH6		LEU1_TX #0 I2C0_SDA #2	
38	PC7	ACMP0_CH7		LEU1_RX #0 I2C0_SCL #2	

Alternate	LOCATION				
Functionality	0	1	2	3	Description
US0_CS	PE13		PC8		USART0 chip select input / output.
US0_RX	PE11		PC10		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10		PC11		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
US1_RX	PC1	PD1			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0			USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4				USART2 clock input / output.
US2_CS	PC5				USART2 chip select input / output.
US2_RX	PC3				USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2				USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

5.4.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32G2322 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.12. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	—	—	—	—	—	PA10	PA9	PA8	—	—	PA5	PA4	PA3	PA2	PA1	PA0
Port B	—	PB14	PB13	—	PB11	—	—	PB8	PB7	—	—	—	—	—	—	—
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	—	—	—	—	—	—	—	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	—	—	—	—	—	—	—	—
Port F	—	—	—	—	—	—	—	—	—	—	PF5	PF4	PF3	PF2	PF1	PF0

Alternate	LOCATION				
Functionality	0	1	2	3	Description
TIM2_CC0	PA8	PA12	PC8		Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9		Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10		Timer 2 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15	UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9		USART0 clock input / output.
US0_CS	PE13	PE4	PC8		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
US1_RX	PC1	PD1			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0			USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5			USART2 clock input / output.
US2_CS	PC5	PB6			USART2 chip select input / output.
US2_RX	PC3	PB4			USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3			USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

5.6.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.17. Alternate functionality overview

Alternate	LOCATION				
Functionality	0	1	2	3	Description
ACMP0_CH0	PC0				Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1				Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2				Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3				Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2			Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8				Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9				Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10				Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11				Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3			Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.

QFN64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
38	PC7	ACMP0_CH7		LEU1_RX #0 I2C0_SCL #2	
39	VDD_DREG	Power supply for on-chip voltage regulator.			
40	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
41	PE4	LCD_COM0		US0_CS #1	
42	PE5	LCD_COM1		US0_CLK #1	
43	PE6	LCD_COM2		US0_RX #1	
44	PE7	LCD_COM3		US0_TX #1	
45	PC12	ACMP1_CH4			CMU_CLK0 #1
46	PC13	ACMP1_CH5	TIM0_CDTI0 #1/3 TIM1_CC0 #0 PCNT0_S0IN #0		
47	PC14	ACMP1_CH6	TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0		
48	PC15	ACMP1_CH7	TIM0_CDTI2 #1/3 TIM1_CC2 #0		DBG_SWO #1
49	PF0		LETIM0_OUT0 #2		DBG_SWCLK #0/1
50	PF1		LETIM0_OUT1 #2		DBG_SWDIO #0/1
51	PF2	LCD_SEG0			ACMP1_O #0 DBG_SWO #0
52	PF3	LCD_SEG1	TIM0_CDTI0 #2		
53	PF4	LCD_SEG2	TIM0_CDTI1 #2		
54	PF5	LCD_SEG3	TIM0_CDTI2 #2		
55	IOVDD_5	Digital IO power supply 5.			
56	PE8	LCD_SEG4	PCNT2_S0IN #1		
57	PE9	LCD_SEG5	PCNT2_S1IN #1		
58	PE10	LCD_SEG6	TIM1_CC0 #1	US0_TX #0	BOOT_TX
59	PE11	LCD_SEG7	TIM1_CC1 #1	US0_RX #0	BOOT_RX
60	PE12	LCD_SEG8	TIM1_CC2 #1	US0_CLK #0	
61	PE13	LCD_SEG9		US0_CS #0	ACMP0_O #0
62	PE14	LCD_SEG10		LEU0_TX #2	
63	PE15	LCD_SEG11		LEU0_RX #2	
64	PA15	LCD_SEG12			

Alternate	LOCATION				
Functionality	0	1	2	3	Description
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0		PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1		PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2		PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0		PA12			Timer 2 Capture Compare input / output channel 0.
TIM2_CC1		PA13			Timer 2 Capture Compare input / output channel 1.
TIM2_CC2		PA14			Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12	PE5			USART0 clock input / output.
US0_CS	PE13	PE4			USART0 chip select input / output.
US0_RX	PE11	PE6			USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7			USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
US1_RX		PD1			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX		PD0			USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5			USART2 clock input / output.
US2_CS	PC5	PB6			USART2 chip select input / output.
US2_RX		PB4			USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).

TQFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
6	PA5	LCD_SEG18	TIM0_CDTI2 #0	LEU1_TX #1	
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PB3	LCD_SEG20	PCNT1_S0IN #1	US2_TX #1	
10	PB4	LCD_SEG21	PCNT1_S1IN #1	US2_RX #1	
11	PB5	LCD_SEG22		US2_CLK #1	
12	PB6	LCD_SEG23		US2_CS #1	
13	PC4	ACMP0_CH4	LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
14	PC5	ACMP0_CH5	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
15	PB7	LFXTAL_P		US1_CLK #0	
16	PB8	LFXTAL_N		US1_CS #0	
17	PA12	LCD_BCAP_P	TIM2_CC0 #1		
18	PA13	LCD_BCAP_N	TIM2_CC1 #1		
19	PA14	LCD_BEXT	TIM2_CC2 #1		
20	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0	LETIM0_OUT0 #1		
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		LEU0_TX #1	
25	PB14	HFXTAL_N		LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			
27	AVDD_0	Analog power supply 0.			
28	PD0	ADC0_CH0	PCNT2_S0IN #0	US1_TX #1	
29	PD1	ADC0_CH1	TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
30	PD2	ADC0_CH2	TIM0_CC1 #3	US1_CLK #1	
31	PD3	ADC0_CH3	TIM0_CC2 #3	US1_CS #1	
32	PD4	ADC0_CH4		LEU0_TX #0	
33	PD5	ADC0_CH5		LEU0_RX #0	
34	PD6	ADC0_CH6	LETIM0_OUT0 #0	I2C0_SDA #1	
35	PD7	ADC0_CH7	LETIM0_OUT1 #0	I2C0_SCL #1	
36	PD8				CMU_CLK1 #1
37	PC6	ACMP0_CH6		LEU1_TX #0 I2C0_SDA #2	

5.9.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.26. Alternate functionality overview

Alternate	LOCATION				
Functionality	0	1	2	3	Description
ACMP0_CH0	PC0				Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1				Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2				Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3				Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2			Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8				Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9				Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10				Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11				Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3			Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.

10.2 QFN64 PCB Layout

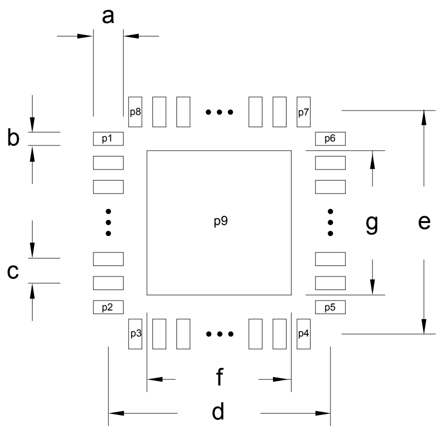

Figure 10.2. QFN64 PCB Land Pattern

Table 10.2. QFN64 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	0.85	P1	1	P8	64
b	0.30	P2	16	P9	65
c	0.50	P3	17		
d	8.90	P4	32		
e	8.90	P5	33		
f	7.20	P6	48		
g	7.20	P7	49		

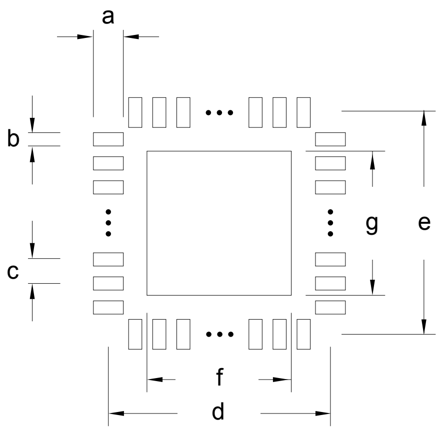

Figure 10.3. QFN64 PCB Solder Mask

Table 10.3. QFN64 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Dim. (mm)
a	0.97	e	8.90
b	0.42	f	7.32
c	0.50	g	7.32

13.5 Revision 1.71

November 21st, 2013

Updated figures.

Updated errata-link.

Updated chip marking.

Added link to Environmental and Quality information.

For devices with a DAC, re-added missing DAC-data.

13.6 Revision 1.70

September 30th, 2013

For devices with an I2C, added I2C characterization data.

Corrected GPIO operating voltage from 1.8 V to 1.85 V.

For devices with an ADC, corrected the ADC resolution from 12, 10 and 6 bit to 12, 8 and 6 bit.

For QFN64 devices, updated the Max V_{ESDCDM} value to 750 V.

Updated Environmental information.

Updated trademark, disclaimer and contact information.

Other minor corrections.

13.7 Revision 1.60

June 28th, 2013

For BGA devices, updated PCB Land Pattern, PCB Solder Mask and PCB Stencil Design figures.

Updated power requirements in the Power Management section.

Removed minimum load capacitance figure and table. Added reference to application note.

Other minor corrections.

13.8 Revision 1.50

September 11th, 2012

Updated the HFRCO 1 MHz band typical value to 1.2 MHz.

Updated the HFRCO 7 MHz band typical value to 6.6 MHz.

For BGA devices, corrected BGA solder balls material from Sn96.5/Ag3/Cu0.5 to SAC105.

Other minor corrections.

13.11 Revision 1.20

December 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Increased max storage temperature.

Added data for <150°C and <70°C on Flash data retention.

Changed latch-up sensitivity test description.

Added IO leakage current.

For LQFP100 devices, updated ESD CDM value.

Added Flash current consumption.

Updated HFRCO data.

Updated LFRCO data.

Added graph for ADC Absolute Offset over temperature.

Added graph for ADC Temperature sensor readout.

13.12 Revision 1.11

November 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Corrected maximum DAC clock speed for continuous mode.

Added DAC sample-hold mode voltage drift rate.

Added pulse widths detected by the HFXO glitch detector.

Added power sequencing information to Power Management section.